# General Purpose Peak EMI Reduction IC

#### **Functional Description**

PCS3P8504A is a versatile, 3.3 V Timing-Safe<sup>TM</sup> Peak EMI reduction IC. PCS3P8504A accepts an input clock either from a fundamental Crystal or from an external reference (AC or DC coupled to XIN/CLKIN) and locks on to it delivering a 1x modulated clock output. PCS3P8504A has a SSON pin for enabling and disabling Spread Spectrum function.

PCS3P8504A has an SSEXTR pin to select different deviations depending upon the value of an external resistor connected between SSEXTR and GND. Modulation Rate (MR) control selects one of the two different Modulation Rates.

PCS3P8504A operates from a 3.3 V supply, and is available in an 8-pin, WDFN(2 mm x 2 mm) package.

#### **General Features**

- 1x, LVCMOS Peak EMI Reduction
- Input frequency:
- ◆ 15 MHz 50 MHz
- Output frequency:
  - ◆ 15 MHz 50 MHz
- Analog Deviation Selection
- ModRate selection option
- Spread Spectrum Enable/Disable
- Supply Voltage:  $3.3 \text{ V} \pm 0.3 \text{ V}$
- 8-pin, WDFN 2 mm x 2 mm (TDFN) Package
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

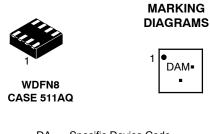
#### Application

• PCS3P8504A is targeted for consumer electronics application like DPF, MFP.

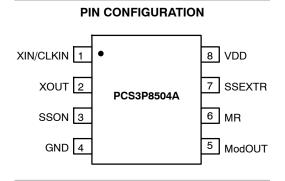


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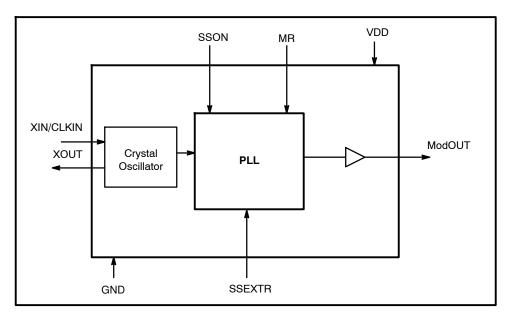
- DA = Specific Device Code
- M = Date Code
- = Pb-Free Device



#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

1



#### Figure 1. Block Diagram

#### Table 1. PIN DESCRIPTION

Pin#	Pin Name	Туре	Description
1	XIN / CLKIN	I	Crystal connection or External reference clock input.
2	XOUT	0	Crystal connection. If using an external reference, this pin should be left open.
3	SSON	I	Spread Spectrum ON/OFF. Spread Spectrum function enabled when HIGH, disabled when LOW. Has an internal pull-up resistor.
4	GND	Р	Ground
5	ModOUT	0	Modulated clock output
6	MR	I	Modulation Rate Select. When LOW selects Low Modulation Rate. Selects High Modulation Rate when pulled HIGH. Has an internal pull-up resistor.
7	SSEXTR	I	Analog Deviation Selection through external resistor to GND.
8	V <sub>DD</sub>	Р	3.3 V supply Voltage.

#### **Table 2. OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>DD</sub>	Supply Voltage	3	3.6	V
T <sub>A</sub>	Operating Temperature	0	70	°C
CL	Load Capacitance		10	pF
C <sub>IN</sub>	Input Capacitance		7	pF

#### Table 3. ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Rating	Unit
$V_{DD}, V_{IN}$	Voltage on any input pin with respect to Ground	-0.5 to +4.6	V
T <sub>STG</sub>	Storage temperature	-65 to +125	°C
Ts	Max. Soldering Temperature (10 sec)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **Table 3. ABSOLUTE MAXIMUM RATING**

Symbol	Parameter	Rating	Unit
TJ	Junction Temperature	150	°C
T <sub>DV</sub>	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **Table 4. DC ELECTRICAL CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
VDD	Supply Voltage		3.0	3.3	3.6	V
V <sub>IL</sub>	Input LOW Voltage				0.8	V
V <sub>IH</sub>	Input HIGH Voltage		2.0			V
١ <sub>١L</sub>	Input LOW Current	V <sub>IN</sub> = 0 V			25	μΑ
I <sub>IH</sub>	Input HIGH Current	$V_{IN} = V_{DD}$			25	μΑ
V <sub>OL</sub>	Output LOW Voltage	I <sub>OL</sub> = 8 mA			0.4	V
V <sub>OH</sub>	Output HIGH Voltage	I <sub>OH</sub> = -8 mA	2.4			V
I <sub>CC</sub>	Static Supply Current	XIN / CLKIN pulled low			50	μΑ
I <sub>DD</sub>	Dynamic Supply Current	Unloaded Output			20	mA
Zo	Output Impedance			30		Ω

#### **Table 5. SWITCHING CHARACTERISTICS**

Parameter	Test Conditions	Min	Тур	Max	Unit
Input Frequency* / ModOUT		15		50	MHz
Duty Cycle (Notes 1 and 2)	Measured at V <sub>DD</sub> / 2	45	50	55	%
Output Rise Time (Notes 1 and 2)	Measured between 20% to 80%			1.8	ns
Output Fall Time (Notes 1 and 2)	Measured between 80% to 20%			1.6	ns
Cycle-to-Cycle Jitter (Note 2)	Unloaded output with SSEXTR OPEN @ 27 MHz		±150	±250	ps
PLL Lock Time (Note 2)	Stable power supply, valid clock presented on XIN / CLKIN			3	ms

\*Functionality with Crystal is guaranteed by design and characterization. Not 100% tested in production. 1. All parameters are specified with10 pF loaded outputs.

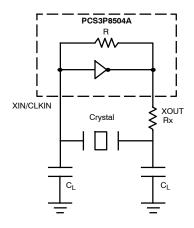
2. Parameter is guaranteed by design and characterization. Not 100% tested in production.

### **TYPICAL CRYSTAL SPECIFICATIONS**

### FUNDAMENTAL AT CUT PARALLEL RESONANT CRYSTAL

Nominal frequency	27 MHz
Frequency tolerance	±50 ppm or better at 25°C
Operating temperature range	-25°C to +85°C
Storage temperature	-40°C to +85°C
Load capacitance (C <sub>P</sub> )	18 pF
Shunt capacitance	7 pF maximum
ESR	25 Ω

NOTE: C<sub>L</sub> is the Load Capacitance and Rx is used to prevent oscillations at overtone frequency of the Fundamental frequency.

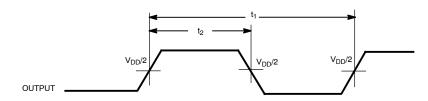


 $C_L = 2 * (C_P - C_S),$ 

Where  $C_P$  = Load capacitance of crystal from crystal vendor datasheet  $C_S$  = Stray capacitance due to  $C_{IN}$ , PCB, Trace etc.

#### Figure 2. Typical Crystal Interface Circuit

## SWITCHING WAVEFORMS



#### Figure 3. Duty Cycle Timing

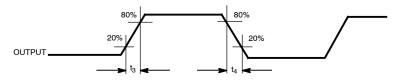
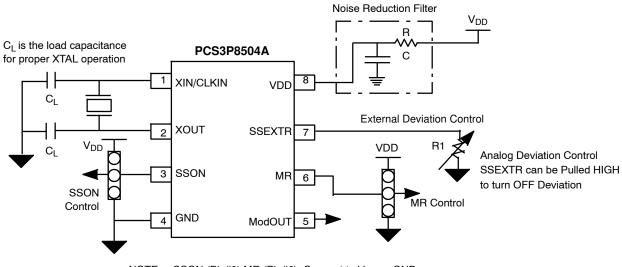
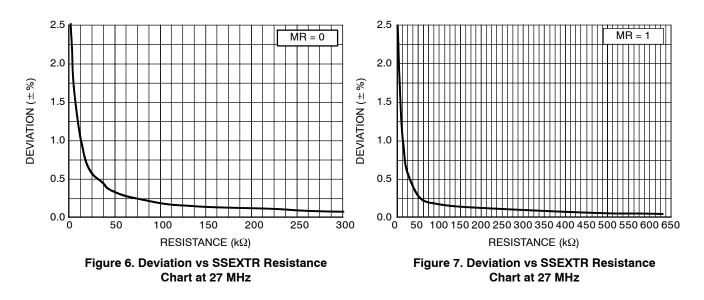


Figure 4. Output Rise/Fall Time



NOTE: SSON (Pin#3) MR (Pin#6): Connect to V<sub>DD</sub> or GND Refer to Pin Description table for Functionality details

#### Figure 5. Application Schematic





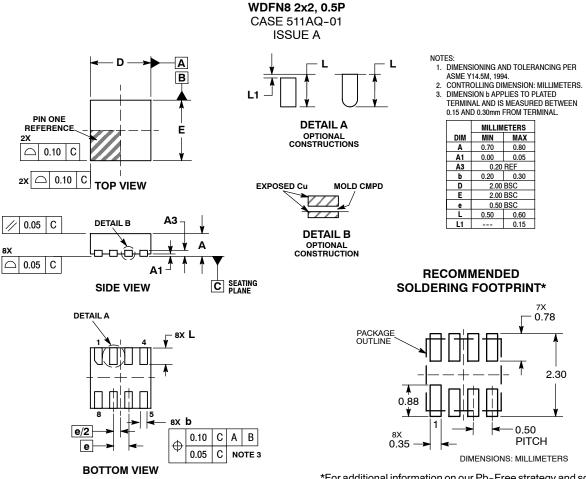
#### **ORDERING INFORMATION**

Part Number	Top Marking	Temperature	Package Type	Shipping <sup>†</sup>
PCS3P8504AG-08CR	DA	0°C to +70°C	8-Pin (2 mm x 2 mm) WDFN(TDFN) (Pb-Free)	Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-Free.

#### PACKAGE DIMENSIONS



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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